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4V Drive Nch+Pch MOSFET

SP8M8

Structure

Silicon N-channel / P-channel MOSFET

Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Smal Surface Mount Package (SOP8).

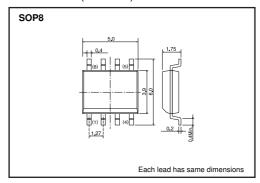
Application

Power switching, DC / DC converter.

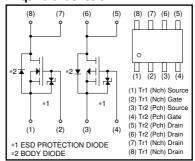
Packaging specifications

	Package	Taping
Type	Code	TB
	Basic ordering unit (pieces)	2500
SP8M8		0

●Dimensions (Unit:mm)



●Equivalent circuit



*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

● **Absolute maximum ratings** (Ta=25°C)

Parameter		Symbol	Lin	Unit	
		Symbol	Nchannel	Pchannel	Offic
Drain-source voltage		V_{DSS}	30	-30	V
Gate-source voltage		V _{GSS}	±20	±20	V
Drain current	Continuous	ID	±6.0	±4.5	Α
	Pulsed	I _{DP} *1	±24	±18	Α
Source current	Continuous	Is	1.6	-1.6	Α
(Body diode)	Pulsed	I _{SP} *1	20	-18	Α
Total power dissipation		P _D *2	2		W
Channel temperature		Tch	150		°C
Storage temperature		Tstg	-55 to +150		°C

Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a)*	62.5	°C / W

^{*}MOUNTED ON A CERAMIC BOARD.

^{*1} Pw≤10μs, Duty cycle≤1% *2 MOUNTED ON A CERAMIC BOARD.

N-ch ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	1	-	±10	μΑ	Vgs=±20V, Vps=0V
Drain-source breakdown voltage	$V_{(BR)\;DSS}$	30	_	_	V	I _D =1mA, V _{GS} =0V
Zero gate voltage drain current	IDSS	-	_	1	μΑ	V _{DS} =30V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	1.0	_	2.5	V	V _{DS} =10V, I _D =1mA
Otatia duain annua an atata		_	21	30		I _D =6.0A, V _{GS} =10V
Static drain-source on-state resistance	R _{DS (on)} *	_	30	42	mΩ	I _D =6.0A, V _{GS} =4.5V
resistance		_	33	47		I _D =6.0A, V _{GS} =4V
Forward transfer admittance	Y _{fs} *	4.0	_	_	S	I _D =6.0A, V _{DS} =10V
Input capacitance	Ciss	_	520	_	pF	V _{DS} =10V
Output capacitance	Coss	_	150	_	pF	V _{GS} =0V
Reverse transfer capacitance	Crss	_	95	_	pF	f=1MHz
Turn-on delay time	t _{d (on)} *	_	9	_	ns	I _D =3A, V _{DD} ≒15V
Rise time	tr *	_	21	_	ns	V _{GS} =10V
Turn-off delay time	td (off) *	_	36	_	ns	R _L =5.0Ω
Fall time	t _f *	-	13	_	ns	R _G =10Ω
Total gate charge	Qg *	-	7.2	-	nC	V _{DD} ≒15V
Gate-source charge	Q _{gs} *	-	1.8	-	nC	V _{GS} =5V
Gate-drain charge	Q _{gd} *		2.8	_	nC	I _D =6.0A

^{*}Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V _{SD} *	_	_	1.2	V	Is=6.4A, VGS=0V

^{*}Pulsed

P-ch
●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	_	_	±10	μΑ	Vgs= ±20V, Vps=0V
Drain-source breakdown voltage	V _{(BR) DSS}	-30	_	_	٧	I _D =-1mA, V _{GS} =0V
Zero gate voltage drain current	IDSS	_	_	-1	μΑ	V _{DS} = -30V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	-1.0	_	-2.5	٧	$V_{DS} = -10V, I_{D} = -1mA$
Otatia duain accuracy as atota		_	40	56		I _D = -4.5A, V _G S= -10V
Static drain-source on-state resistance	R _{DS (on)} *	_	57	80	mΩ	$I_D = -2.5A$, $V_{GS} = -4.5V$
resistance		_	65	90		$I_D = -2.5A$, $V_{GS} = -4.0V$
Forward transfer admittance	Y _{fs} *	3.5	_	_	S	$I_D = -2.5A$, $V_{DS} = -10V$
Input capacitance	Ciss	_	850	_	pF	V _{DS} = -10V
Output capacitance	Coss	_	190	_	pF	V _G S=0V
Reverse transfer capacitance	Crss	_	120	_	pF	f=1MHz
Turn-on delay time	t _{d (on)} *	_	10	_	ns	I _D = −2.5A, V _{DD} ≒ −15V
Rise time	tr *	_	25	_	ns	V _{GS} = -10V
Turn-off delay time	td (off) *	_	60	_	ns	R _L =6.0Ω
Fall time	t _f *	-	25	_	ns	R _G =10Ω
Total gate charge	Q _g *	-	8.5	_	nC	V _{DD} ≒ −15V
Gate-source charge	Q _{gs} *	-	2.5	_	nC	V _{GS} = -5V
Gate-drain charge	Q _{gd} *	-	3.0	_	nC	I _D = -4.5A

^{*}Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	VsD	_	_	-1.2	٧	Is=-1.6A, VGS=0V

N-ch

•Electrical characteristic curves

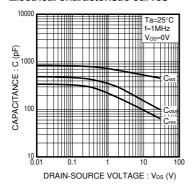


Fig.1 Typical Capacitance vs. Drain-Source Voltage

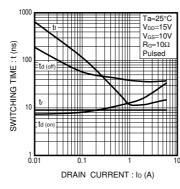


Fig.2 Switching Characteristics

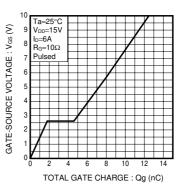


Fig.3 Dynamic Input Characteristics

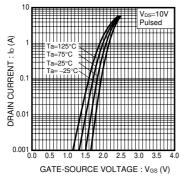


Fig.4 Typical Transfer Characteristics

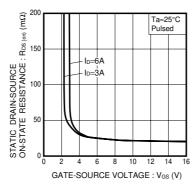


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

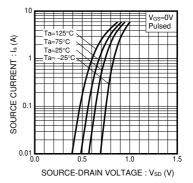


Fig.6 Source Current vs. Source-Drain Voltage

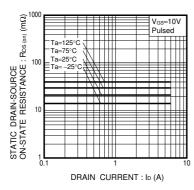


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

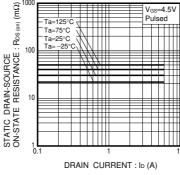


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

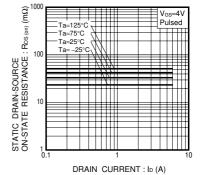


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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P-ch

•Electrical characteristic curves

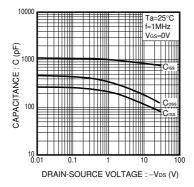


Fig.1 Typical Capacitance vs. Drain-Source Voltage

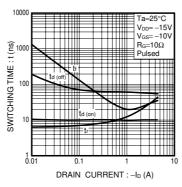


Fig.2 Switching Characteristics

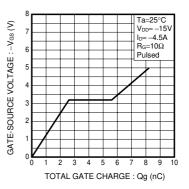


Fig.3 Dynamic Input Characteristics

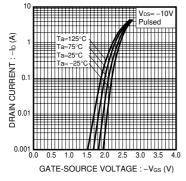


Fig.4 Typical Transfer Characteristics

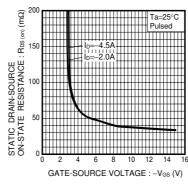


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

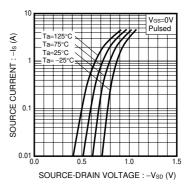


Fig.6 Source Current vs. Source-Drain Voltage

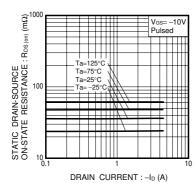


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

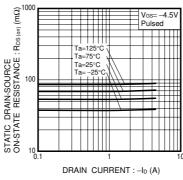


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

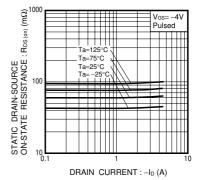


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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